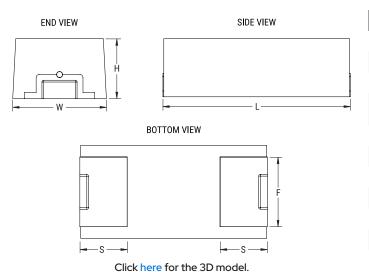


T597S226M010APE200

Aliases (FPUA21A226M200B)

T597, Tantalum, Polymer Tantalum, Reduced Volume, 22 uF, 20%, 10 VDC, SMD, Polymer, Molded, Low ESR, AEC-Q200, 200 mOhms, 3216, 1.2 mm, 0.8 mm



General Information		
Series	T597	
Dielectric	Polymer Tantalum	
Style	SMD Chip	
Description	SMD, Polymer, Molded, Low ESR, AEC-Q200	
Features	Face Down, Automotive	
RoHS	Yes	
Termination	Nickel Palladium Gold	
Qualifications	AEC-Q200	
AEC-Q200	Yes	
Typical Component Weight	26.2 mg	
Miscellaneous	Under Development. Engineering samples are available upon request.	
Shelf Life	52 Weeks	
MSL	3	

Dimensions	
L	3.2mm +/-0.2mm
W	1.6mm +/-0.2mm
Н	1.1mm +/-0.1mm
S	0.8mm +/-0.2mm
F	1.2mm +/-0.1mm
Packaging Specifications	
Packaging	T&R, 178mm

3000

Packaging Quantity

Capacitance	22 uF	
Tolerance	20%	
Voltage DC	10 VDC (105C), 6.7 VDC (125C)	
Temperature Range	-55/+125°C	
Rated Temperature	105°C	
Humidity	85C, 85% RH, load, 1000 Hours	
Dissipation Factor	10% 120Hz 25C	
Failure Rate	N/A	
ESR	200 mOhms (100kHz 25C)	
Ripple Current	570 mA (rms, 100kHz 45C), 513 mA (rms, 85C), 142.5 mA (rms, 125C)	

	LSIX	200 1110111113 (100K1 12 23C)
	Ripple Current	570 mA (rms, 100kHz 45C), 513 mA (rms, 85C), 142.5 mA (rms, 125C)
	Leakage Current	66 uA (5min 25°C)

Specifications

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

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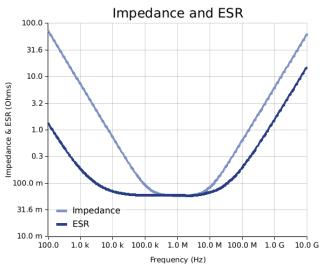
T597S226M010APE200

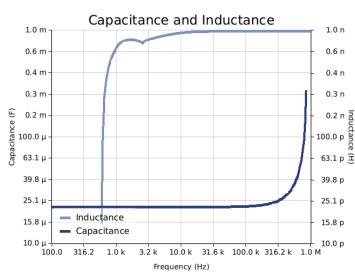
Aliases (FPUA21A226M200B)

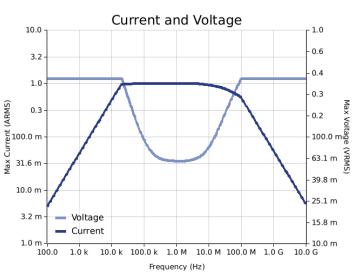
T597, Tantalum, Polymer Tantalum, Reduced Volume, 22 uF, 20%, 10 VDC, SMD, Polymer, Molded, Low ESR, AEC-Q200, 200 mOhms, 3216, 1.2 mm, 0.8 mm

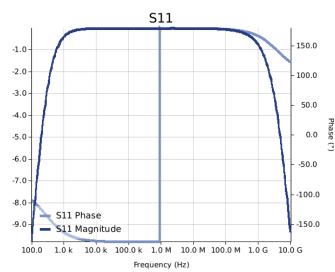
Simulations

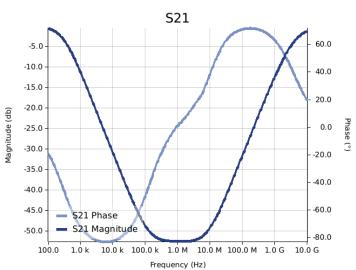
For the complete simulation environment please visit Y-SIM.











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T597S226M010APE200

Aliases (FPUA21A226M200B)

T597, Tantalum, Polymer Tantalum, Reduced Volume, 22 uF, 20%, 10 VDC, SMD, Polymer, Molded, Low ESR, AEC-Q200, 200 mOhms, 3216, 1.2 mm,

These are simulations.

This is not a specification!

The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

The responses shown do not represent a specified or implied maximum capability of the device for all applications.

- The ESR used for ripple "Ripple Current/Voltage vs. Frequency" plots is the ESR at ambient temperature.

- The ESR in the "Temperature Rise vs. Ripple Current" plots is the ESR at ambient temperature. The ESR in the "Temperature Rise vs. Ripple Current" plots is adjusted to each incremental temperature rise before the power and ripple current is calculated. The effects shown herein are based on measured data from a multiple part sample of the parts in question. Ripple capability of this device will be factored by thermal resistance (Rth) created by circuit traces (addi affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

 The peak voltages generated in the "Temperature Rise vs. Combined Ripple Currents" plot are calculated for each frequency and are not combined with voltages
- generated at any other harmonics.

 Please consult with the catalog or field applications engineer for maximum capability of the device in specific applications.

All product information and data (collectively, the "Information") are subject to change without notice.

KEMET K-SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels. The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation effects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

All Information given herein is believed to be accurate and reliable, but is presented without guarantee, warranty, or responsibility of any kind, expressed or implied. Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute – and we specifically disclaim – any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

If you have any questions please contact K-SIM.

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